

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5175013

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHIJIE CHEN	09/27/2018
RECEIVING PARTY DATA	
Name:	Silergy Semiconductor Technology (Hangzhou) LTD.
Street Address:	A1501 Technology Mansion, No. 90 Wensan Road
City:	Hangzhou, ZheJiang Province
State/Country:	CHINA
Postal Code:	310012
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16152533
CORRESPONDENCE DATA	
Fax Number:	(408)353-9570
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(408)353-9570
Email:	mike@stephenspatents.com
Correspondent Name:	MICHAEL C. STEPHENS, JR.
Address Line 1:	22779 MONTROSE COURT
Address Line 4:	LOS GATOS, CALIFORNIA 95033
ATTORNEY DOCKET NUMBER:	SILG2017P49US
NAME OF SUBMITTER:	MICHAEL C. STEPHENS, JR.
SIGNATURE:	/Michael C. Stephens, Jr./
DATE SIGNED:	10/05/2018
Total Attachments: 2	
source=SILG2017P49US_Assignment#page1.tif	
source=SILG2017P49US_Assignment#page2.tif	

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, the person(s) named below (referred herein as "INVENTOR" whether singular or plural) has sold, assigned, and transferred and does hereby sell, assign, and transfer to **SILERGY SEMICONDUCTOR TECHNOLOGY (HANGZHOU) LTD.**, having a place of business at A1501 Technology Mansion, No. 90 Wensan Road, Hangzhou, Zhejiang Province, China 310012 ("ASSIGNEE"), for itself and its successors, transferees, and assignees, the following:

1. The entire worldwide right, title, and interest in all inventions and improvements ("SUBJECT MATTER") that are disclosed in the provisional application filed under 35 U.S.C. §111(b) or non-provisional application filed under 35 U.S.C. §111(a) and entitled **CHIP PACKAGE STRUCTURE AND METHOD FOR MANUFACTURING THE SAME** ("APPLICATION"), which:

was filed on 10/5/18, now bearing U.S. serial number 16/122,822; and

2. The entire worldwide right, title, and interest in and to:
(a) the APPLICATION; (b) all applications claiming priority from the APPLICATION; (c) all divisional, continuation, substitute, renewal, reissue, and other related applications thereto which have been or may be filed in the United States or elsewhere in the world; (d) all patents (including reissues and re-examinations) which may be granted on the applications set forth in (a), (b), (c) and (d) above; and (e) all right of priority in the APPLICATION, together with all rights to recover damages for infringement of provisional rights.

INVENTOR agrees that ASSIGNEE may apply for and receive patents for SUBJECT MATTER in ASSIGNEE's own name.

INVENTOR agrees to do the following, when requested, and without further consideration, in order to carry out the intent of this Assignment: (1) execute all assignments, oaths, powers of attorney, applications, and other papers (and/or documents) necessary or desirable to fully secure to ASSIGNEE the rights, titles and interests herein conveyed; (2) communicate to ASSIGNEE all known facts relating to the SUBJECT MATTER; and (3) generally do all lawful acts that ASSIGNEE shall consider desirable for securing, maintaining, and enforcing worldwide patent protection relating to the SUBJECT MATTER and for vesting in ASSIGNEE the rights, titles, and interests herein conveyed. INVENTOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE hereunder.

INVENTOR represents that INVENTOR has the rights, titles, and interests to convey as set forth herein, and covenants with ASSIGNEE that the INVENTOR has not made and will not hereafter make any assignment, grant, mortgage, license, or other agreement affecting the rights, titles, and interests herein conveyed.

INVENTOR grants the attorney(s) of record the power to insert on this Assignment any further identification, including an application serial number and filing date, as may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

PATENT

Title of Document: ASSIGNMENT

Re:

Title: CHIP PACKAGE STRUCTURE AND METHOD FOR MANUFACTURING THE
SAME

Filed: (if applicable) 10/05/2018

Atty. Docket No.: SILG2017P49US

Serial No.: (if applicable) 16/152,583

This Assignment may be executed in one or more counterparts, each of which shall be deemed an original and all of which may be taken together as one and the same Assignment.

Name and Signature _____

Date of Signature _____

Shijie Chen

9/27/2018

Shijie Chen